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Intro to Memory Packaging Quiz

Reviewed 2025

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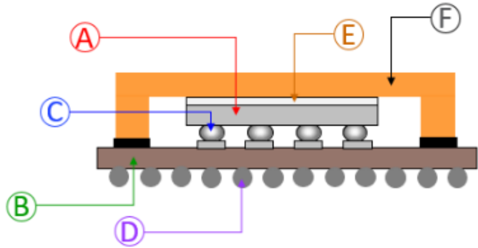
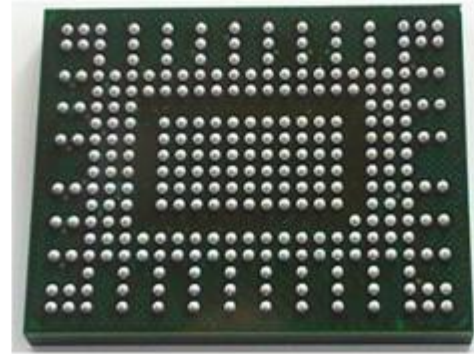
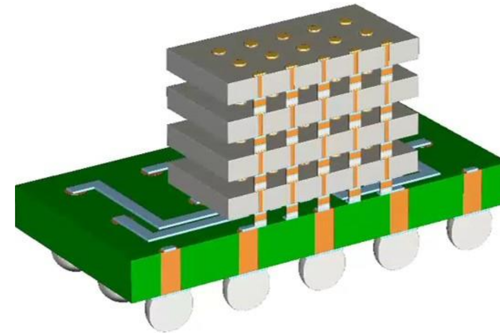
Intro to Memory Packaging – Quiz Ideas



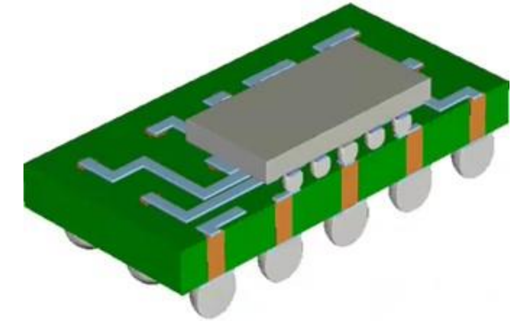
1) Item A in the schematic represents a silicon die. What do we collectively call items B, C, D, E, and F in semiconductor technology?
   A. Packaging
   B. Heat dissipation
   C. Interposer
   D. Primary and Secondary interconnects



2) The balls in the BGA (Ball Grid Array) package shown are an example of:
   A. Primary interconnects
   B. Secondary interconnects
   C. Redistribution layer
   D. Heat sink



3) What type of package is shown in the image?
   A. Package-on-Package
   B. Wire bonding
   C. Flip Chip
   D. TSV (Through Silicon Vias)



4) What type of package is shown in the image?
   A. Package-on-Package
   B. Wire bonding
   C. Flip Chip
   D. TSV (Through Silicon Vias)

Intro to Memory Packaging – Quiz Ideas

5) What is the purpose of Packaging? Select the best answer.
   A. Electrical interface between the chip and outer circuitry
   B. Physical protection of the die
   C. Heat dissipation
   D. All of the above

6) Metal lids are an example of:
   A. Heat dissipation strategy
   B. Primary interconnects
   C. Secondary interconnects
   D. Interposer

7) Which packaging technology is best suited for low parasitic voltage loss?
   A. Direct wirebond
   B. Cascaded wirebond
   C. Package-on-Package
   D. Flip chip

8) What major is preferred for a career in Semiconductor Packaging Technology? Select the best answer.
   A. Electrical Engineering
   B. Mechanical Engineer
   C. Material Science
   D. Chemistry
   E. Physics
   F. All of the above are needed for interdisciplinary teams to successfully tackle packaging challenges

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